APPLI-TEC
THERMOSET ADHESIVE SOLUTIONS
ISO 9001 / AS9100 CERTIFIED

# 5340 Epoxy

## Thermally conductive, two-part epoxy packaged in 1:1 cartridges

5340 is designed for potting and bonding applications that require thermal conductivity and high lap-shear strength. Conveniently packaged in easy-to-use cartridges, 5340 meets NASA outgas standards for high reliability electronics and aerospace applications.

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| **UNCURED** | |
| Pot Life @ 25°C | 90 Minutes |
| Viscosity, Part A, @ 25°C | 115,000 cPs |
| Viscosity, Part B, @ 25°C | 140,000 cPs |
| Viscosity, Mixed, @ 25°C | 120,000 cPs |
| Thixotropic Index | 1.6 |
| Shelf Life @ 15-25°C | 6 Months from Date of Shipment |
| Mix Ratio A:B | 100:100 Parts By Volume |
| **CURED OPTIONS** | 2 hours @ 80°C  24 hrs @ 25°C (Handling)<br>7 Days @ 25°C (Full Cure) |
| **CURED PROPERTIES** | Based on cure of 2 hours @ 80°C |
| Color | Off-White |
| Shore D Hardness | 90 |
| Glass Transition Temp (°C) | 70 |
| Density (g/cc) | 2.19 |
| Lap Shear (psi) | 2400 |
| **ELECTRICAL PROPERTIES** | Based on cure of 2 hours @ 80°C |
| Dielectric Constant, 1MHz | 4.44 |
| Dissipation Factor, 1MHz | 0.013 |
| Dielectric Strength (volts/mil) | 550 |
| Volume Resistivity (ohm-cm) | 1.7E+15@ 500 VDC |
| **THERMAL PROPERTIES** | Based on cure of 2 hours @ 80°C |
| Glass Transition Temp (°C) | 70 |
| Thermal Conductivity (W/mK) | 1 |
| Operating Temperature (°C) | -50 to 150 |
| **OUTGASSING PROPERTIES** | Based on cure of 2 hours @ 80°C |
| TML (%) | 0.42 |
| CVCM (%) | 0.02 |
| WVR (%) | 0.16 |
| **ACOUSTIC PROPERTIES** | |
| Velocity (m/s) | 2909 |
| Impedance (MRayls) | 6.369 |

### KEY FEATURES

- Electrically Isolating
- Thermally Conductive
- Convenient Mix Ratio
- Flowable
- √ RoHS Compliant


**Chat with a specialist:**

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**Rev B** **3-7-24**

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|---|---|
| Loss (dB/cm-MHz) | -9.41 |
| Density (g/cc) | 2.19 |